

**Surface Mount Superfast Recovery Rectifier**

Reverse Voltage – 50 to 600 V

Forward Current – 3 A

**FEATURES**

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

**MECHANICAL DATA**

- Case: SMBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 57mg / 0.002oz

**Absolute Maximum Ratings and Characteristics**

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

**PINNING**

PIN	DESCRIPTION
1	Cathode
2	Anode

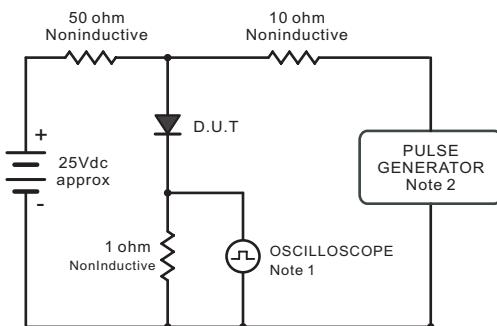


Simplified outline SMBF and symbol

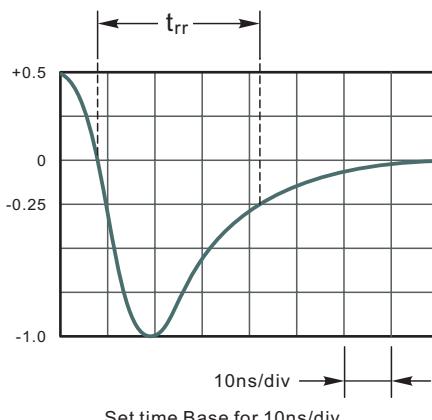
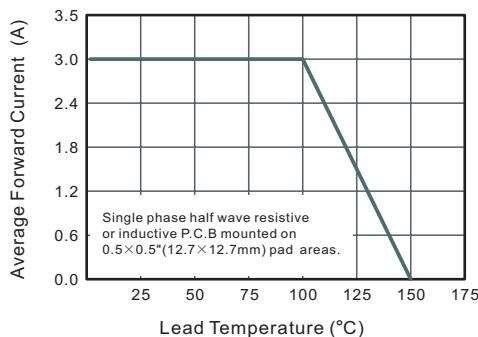
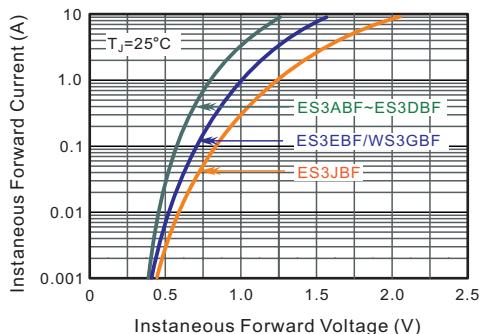
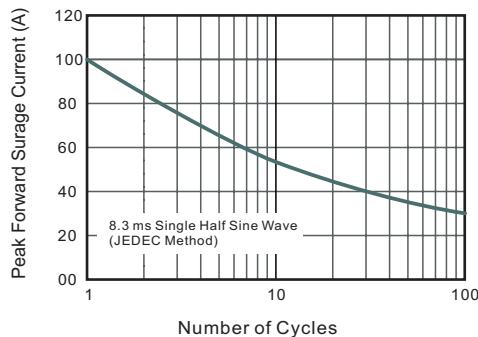
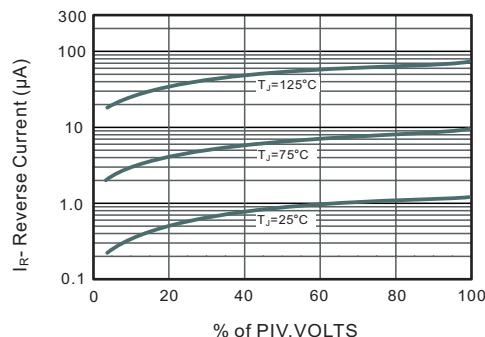
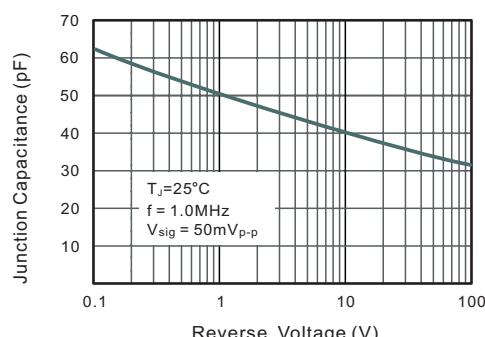
Parameter	Symbols	ES3ABF	ES3BF	ES3CBF	ES3DBF	ES3EBF	ES3GBF	ES3JBF	Units		
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	50	100	150	200	300	400	600	V		
Maximum RMS voltage	V <sub>RMS</sub>	35	70	105	140	210	280	420	V		
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	150	200	300	400	600	V		
Maximum Average Forward Rectified Current at T <sub>L</sub> = 100 °C	I <sub>F(AV)</sub>	3							A		
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	100							A		
Maximum Forward Voltage at 3A	V <sub>F</sub>	1			1.25		1.68		V		
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta = 125 °C	I <sub>R</sub>	5 100							µA		
Typical Junction Capacitance	C <sub>j</sub>	45							pF		
Maximum Reverse Recovery Time at I <sub>F</sub> =0.5A, I <sub>R</sub> =1A, I <sub>rr</sub> =0.25A	t <sub>rr</sub>	35							ns		
Typical Thermal Resistance <sup>2)</sup>	R <sub>θJA</sub>	55							°C/W		
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55 ~ +150							°C		

 1) Measured with I<sub>F</sub> = 0.5 A, I<sub>R</sub> = 1 A, I<sub>rr</sub> = 0.25 A

2) P.C.B. mounted with 0.5 X 0.5" (12.7 X 12.7 mm) copper pad areas.

**Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram**


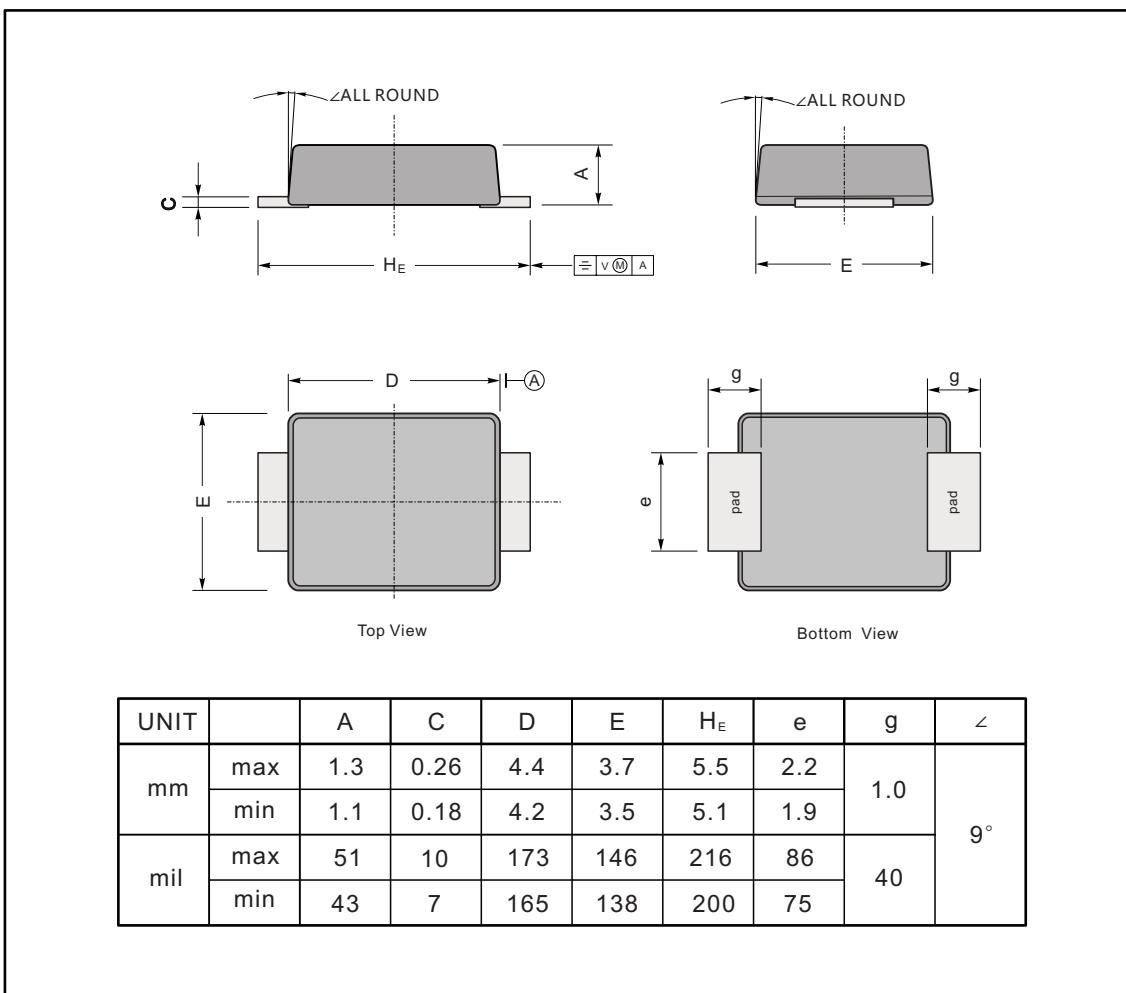
Note: 1. Rise Time = 7ns, max.  
 Input Impedance = 1megohm,22pF.  
 2. Ries Time =10ns, max.  
 Source Impedance = 50 ohms.


**Fig.2 Maximum Average Forward Current Rating**

**Fig.4 Typical Forward Characteristics**

**Fig.6 Maximum Non-Repetitive Peak Forward Surge Current**

**Fig.3 Typical Reverse Characteristics**

**Fig.5 Typical Junction Capacitance**


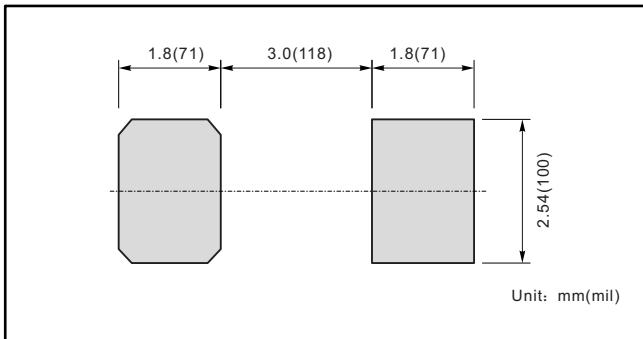
## PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMBF



### The recommended mounting pad size



### Marking

Type number	Marking code
ES3ABF	E3AB
ES3BBF	E3BB
ES3CBF	E3CB
ES3DBF	E3DB
ES3EBF	E3EB
ES3GBF	E3GB
ES3JBF	E3JB